



# CUSTOMER ADVISORY

## ADV1812

### Conversion to Intel Packing Methodology

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#### Change Description:

Intel® Programmable Solutions Group (“Intel PSG”, formerly Altera) is notifying customers of a packing conversion.


As a part of integration efforts, Intel PSG is beginning the transition to Intel packing methods for tray, tube, and tape and reel packed products.

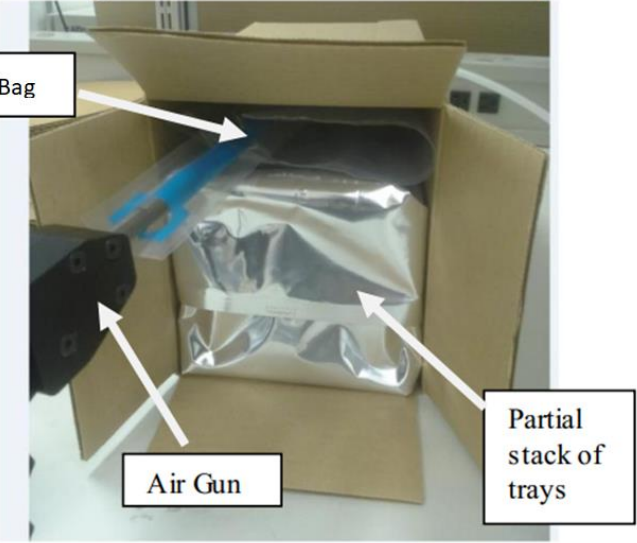
Once the conversion is in effect, customers can expect to receive units in one of several packing options. The following describes the packing options for tray, tube, and tape and reel packed products:

**Table 1: Tray Packing Method**

	Tray Packing	Description
<b>Packing Method (Option 1)</b>		Bubble wrapped trays





		
<b>Packing Method (Option 2)</b>		Use of plastic shim at the top and bottom of the tray stack.





Tray Packing (Partial Packing)		Description
<b>Packing Method (Option 1)</b>	 <p>Bubble Wrap →</p> <p>↑ Partial Stack of Trays</p>	Bubble wrap on top of tray stack

<p><b>Packing Method (Option 2)</b></p>		<p>Air bag on top of tray stack</p>
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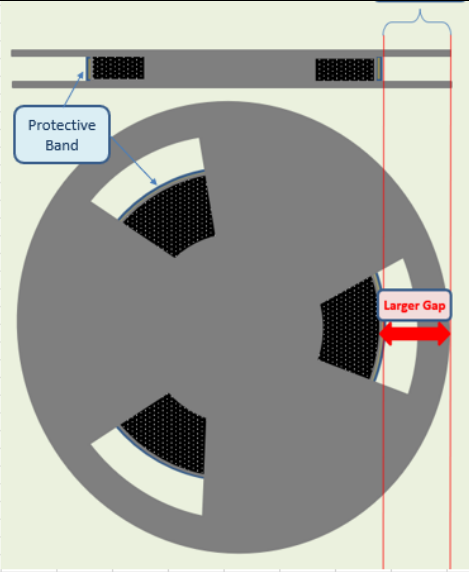
**Table 2: Tube Packing Method**

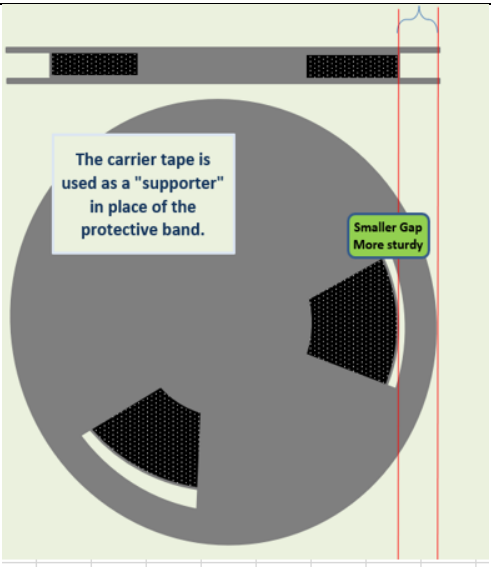

Note: Customers will receive tube packing either with or without Altera logo

<p><b>Tube Packing (Dry Packed)</b></p>	
 <p>Tubes tied with rubber band before placement inside the Moisture Barrier Bag (MBB).</p>	 <p>Vacuum-sealed MBB and placed inside the box</p>
 <p>Bubble sheet filler if not full box.</p>	 <p>Covered with foam on top of the package/bubble wrap</p>

Tube Packing (Non-Dry Packed)	
 <p>Tubes tied with pink rubber band before placement inside the box.</p>	 <p>Tubes inserted in box.</p>
 <p>Bubble sheet filler if not full box.</p>	 <p>Covered with foam on top of the package/bubble wrap</p>

**Table 3: Tape and Reel Packing Method**

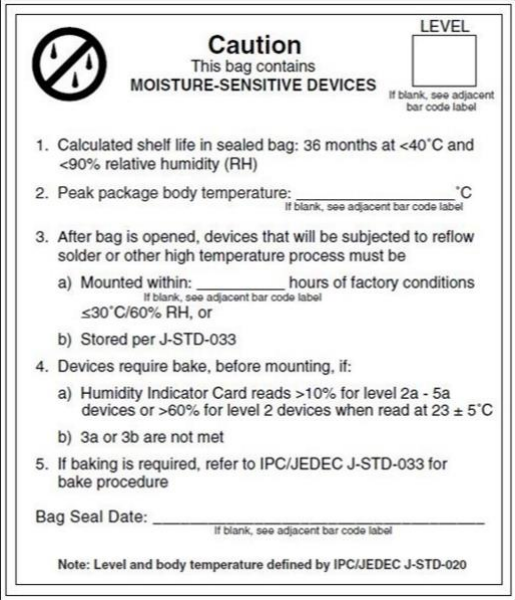

	Tape and Reel Packing	Description
<p><b>Reel Protection (Option 1)</b></p>		<p>Protective band used to provide an extra gap for support</p>

<p><b>Reel Protection (Option 2)</b></p>	 <p>The carrier tape is used as a "supporter" in place of the protective band.</p> <p>Smaller Gap More sturdy</p>	<p>Carrier tape used as support by increasing the trailer and leader pocket quantity</p>
<p><b>Packing Method (Dry Pack)</b></p>		<p>Desiccant and Humidity Indicator Card (HIC) on top of reel</p> <p>Reel packed in MBB in box</p>

<p><b>Packing Method (Non-Dry Pack) (Option 1)</b></p>		<p>Reel placed in I-Box</p>
<p><b>Packing Method (Non-Dry Pack) (Option 2)</b></p>		<p>Reel wrapped in bubble sheets in box</p>

## Added Caution Label

MBB label for Tray, Tube, and Tape and Reel packing will contain an additional caution label.

Original MBB Label	Added Caution Label
 <p><b>Caution</b> This bag contains <b>MOISTURE-SENSITIVE DEVICES</b></p> <p>LEVEL <input type="checkbox"/></p> <p>If blank, see adjacent bar code label</p> <ol style="list-style-type: none"> <li>1. Calculated shelf life in sealed bag: 36 months at &lt;math&gt;40^{\circ}\text{C}&lt;/math&gt; and &lt;math&gt;&lt;90\%&lt;/math&gt; relative humidity (RH)</li> <li>2. Peak package body temperature: _____ <math>^{\circ}\text{C}</math> If blank, see adjacent bar code label</li> <li>3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be             <ol style="list-style-type: none"> <li>a) Mounted within: _____ hours of factory conditions If blank, see adjacent bar code label <math>\leq 30^{\circ}\text{C}/60\% \text{RH}</math>, or</li> <li>b) Stored per J-STD-033</li> </ol> </li> <li>4. Devices require bake, before mounting, if:             <ol style="list-style-type: none"> <li>a) Humidity Indicator Card reads &gt;10% for level 2a - 5a devices or &gt;60% for level 2 devices when read at <math>23 \pm 5^{\circ}\text{C}</math></li> <li>b) 3a or 3b are not met</li> </ol> </li> <li>5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure</li> </ol> <p>Bag Seal Date: _____ If blank, see adjacent bar code label</p> <p>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</p>	 <p><b>ATTENTION</b> OBSERVE PRECAUTIONS FOR HANDLING ELECTRONIC SENSITIVE DEVICES</p> <p>OTHER OTHER</p> <p>500369846</p>

The two labels will appear on the MBB together, as shown below:



## Recommended Action

Customers are being notified to take note of this packing conversion. Please note that once the conversion is in effect, customers may receive units in one of several packing options.

## Products Affected:

All Intel PSG Products

## Reason for Change:

The purpose of this conversion is to standardize and align the packing methodology of PSG products to that of Intel.

## Change Implementation

Table 4

<i>Milestone</i>	<i>Date</i>
Date Packing Conversion is in Effect	Now

## Contact

For more information, please contact Sales or Customer Quality Engineering (CQE) in your region, or submit a Service Request at the [My Intel](#) support page.



## Customer Notifications Subscription

Customers that have subscribed to Intel PSG's customer notification mailing list will receive the PCN document automatically via email.

If you would like to receive customer notifications by email, please subscribe to our customer notification mailing list at:

<https://www.intel.com/content/www/us/en/programmable/my-intel/mal-emailsub/technical-updates.html>

## Revision History

Date	Rev	Description
08/01/2018	1.0.0	Initial Release

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